

KP-3216SGD

SUPER BRIGHT GREEN

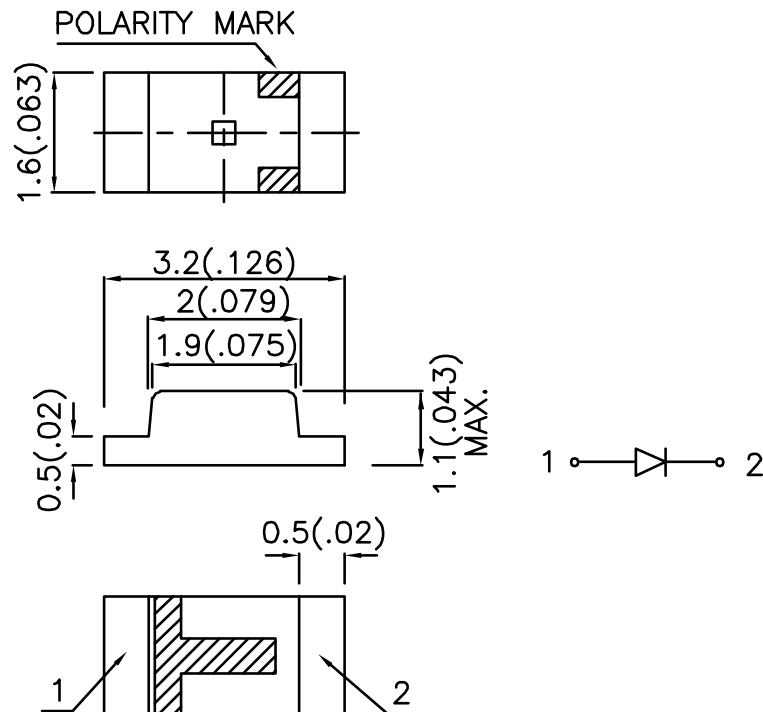
Features

- 3.2mmx1.6mm SMT LED, 1.1mm THICKNESS.
- LOW POWER CONSUMPTION.
- WIDE VIEWING ANGLE.
- IDEAL FOR BACKLIGHT AND INDICATOR.
- VARIOUS COLORS AND LENS TYPES AVAILABLE.
- PACKAGE : 2000PCS / REEL.
- ROHS COMPLIANT.

Description

The Super Bright Green source color devices are made with Gallium Phosphide Green Light Emitting Diode.

Package Dimensions



Notes:

1. All dimensions are in millimeters (inches).
2. Tolerance is ± 0.2 (0.008") unless otherwise noted.
3. Specifications are subject to change without notice.

Selection Guide

Part No.	Dice	Lens Type	Iv (mcd) @ 20mA		Viewing Angle
			Min.	Typ.	θ1/2
KP-3216SGD	SUPER BRIGHT GREEN (GaP)	GREEN DIFFUSED	4	15	120°

Note:

1. θ1/2 is the angle from optical centerline where the luminous intensity is 1/2 the optical centerline value.

Electrical / Optical Characteristics at TA=25°C

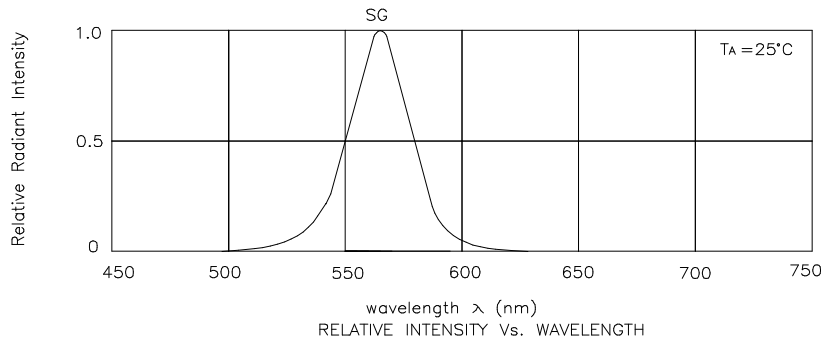
Symbol	Parameter	Device	Typ.	Max.	Units	Test Conditions
λ _{peak}	Peak Wavelength	Super Bright Green	565		nm	I _F =20mA
λ _D	Dominate Wavelength	Super Bright Green	568		nm	I _F =20mA
Δλ _{1/2}	Spectral Line Half-width	Super Bright Green	30		nm	I _F =20mA
C	Capacitance	Super Bright Green	15		pF	V _F =0V;f=1MHz
V _F	Forward Voltage	Super Bright Green	2.2	2.5	V	I _F =20mA
I _R	Reverse Current	Super Bright Green		10	uA	V _R = 5V

Absolute Maximum Ratings at TA=25°C

Parameter	Super Bright Green	Units
Power dissipation	105	mW
DC Forward Current	25	mA
Peak Forward Current [1]	140	mA
Reverse Voltage	5	V
Operating / Storage Temperature	-40°C To +85°C	

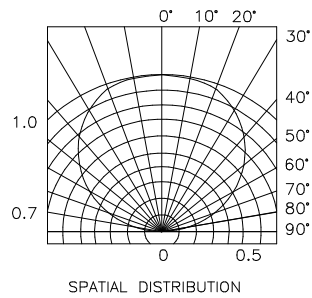
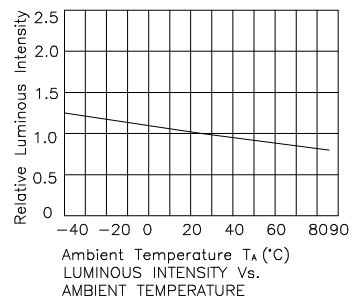
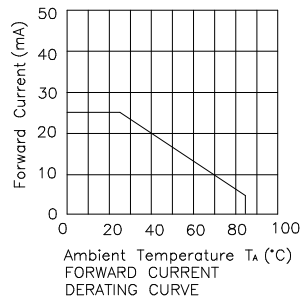
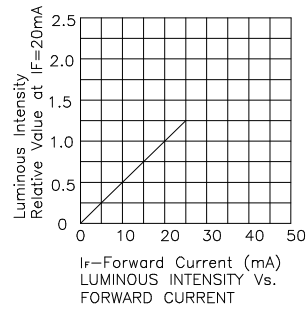
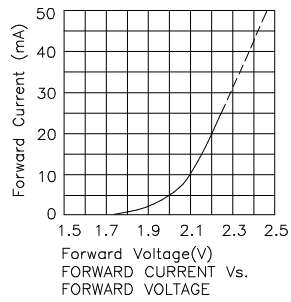
Note:

1. 1/10 Duty Cycle, 0.1ms Pulse Width.



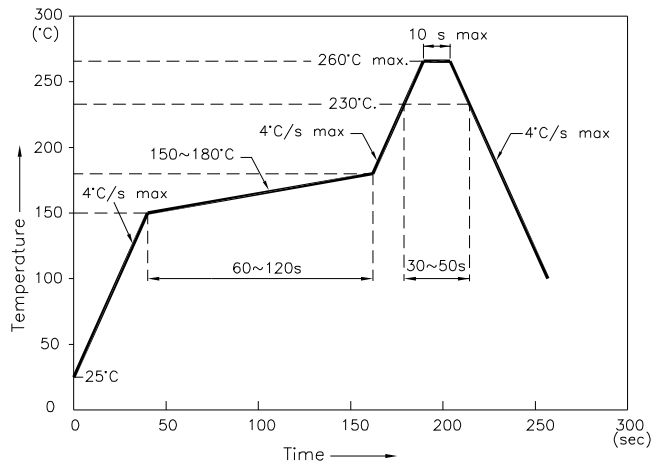
Super Bright Green

KP-3216SGD



KP-3216SGD

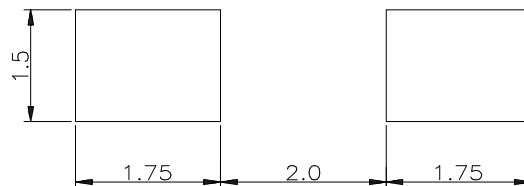
Reflow Soldering Profile For Lead-free SMT Process.



NOTES:

1. We recommend the reflow temperature 245°C(+/-5°C). The maximum soldering temperature should be limited to 260°C.
2. Don't cause stress to the epoxy resin while it is exposed to high temperature.
3. Number of reflow process shall be 2 times or less.

Recommended Soldering Pattern (Units : mm)



Tape Specifications (Units : mm)

